Project	**IEEE 802.16 Broadband Wireless Access Working Group <http://ieee802.org/16>**
Title	**Minutes of IEEE 802.16 Session #68**
Date Submitted	**2 August 2010**
Source	Scott Probasco Voice: 1-469-939-9378 Nokia, Inc. scott.probasco@nokia.com
Abstract	IEEE 802.16 Session #68 Minutes (San Diego, California)
Purpose	To record the minutes of the IEEE 802.16 Working Group Opening and Closing Plenary meetings at Session #68. For approval at Session #69.
Release	The contributor is familiar with the IEEE-SA Copyright Policy <http://standards.ieee.org/IPR/copyrightpolicy.html>.
Patent Policy and Procedures	The contributor is familiar with the IEEE-SA Patent Policy and Procedures: <http://standards.ieee.org/guides/bylaws/sect6-7.html#6> and <http://standards.ieee.org/guides/opman/sect6.html#6.3>. Further information is located at <http://standards.ieee.org/board/pat/pat-material.html> and <http://standards.ieee.org/board/pat>.

Minutes of IEEE 802.16 Session #68

IEEE 802.16 Working Group
San Diego, California
July 12 - 15, 2010

IEEE 802.16 Session #68 Opening Plenary Meeting

Monday July 12, 2010, 13:22 – 15:22 hours.

Opening

The Working Group (WG) meeting was called to order by Dr. Roger Marks at 13:22 hours local time. He welcomed the attendees to Session #68 of the IEEE 802.16 WG. Roger provided the URL for the local server containing the welcome page, links to the upload facilities, attendance, agenda, etc. Roger explained the web site and the WirelessMAN Interactive Calendar.

Roger introduced himself as Chair of the Working Group (WG). Roger is affiliated with the WiMAX Forum. Vice Chair Jose Puthenkulam, affiliated with Intel, and Secretary Scott Probasco, affiliated with Nokia, introduced themselves. Treasurer Scott Migaldi was introduced in absence. The Chair provided information related to logistics and meeting registration and invited people to get aquainted with each other during the week and indicated that the members will be happy to assist the new attendees.

Membership and Voting

The Chair described types of Membership in the WG as well as the rights and obligations of Membership in the WG. At the beginning of the Session there were 300 Members (<http://ieee802.org/16/members.html>) of the WG. Potential Members (<http://ieee802.org/16/members_pot.html>), Members in Peril (<http://ieee802.org/16/members_peril.html>) and Observers (<http://ieee802.org/16/observers.html>) were also noted. Members of the WG were advised to verify that a Voting Token was printed on their registration badge.

The attendees were informed that acquiring and retaining Membership (reference <http://ieee802.org/16/membership.html>) in the WG depends on logging attendance correctly in the IEEE Automated Meeting Attendance Tool ("IMAT"). The Chair demonstrated the method of registering in the IMAT system. Attendance software's "Affiliation" field is the appropriate Affiliation per IEEE-SA affiliation disclosure requirements (reference <http://standards.ieee.org/faqs/affiliationFAQ.html>) and will be reported as such. The Chair explained that entering "WG802.16" as affiliation is invalid and no participation credit will be given in that case. Attendees were advised that they must record at least 29 of the 38 possible credit hours in the IMAT attendance system in order to ensure "Participation" status for Session #68 of IEEE 802.16 WG. The Chair noted that attendance credit will be granted to 802.16 Members for participation in IEEE 802.18, 802.19, 802.21, and 802.23.

Approvals

The Chair reviewed the agenda and asked for comments or concerns. Adjustments were made to the agenda. The Opening Plenary Meeting agenda was approved by unanimous consent as presented (reference <http://ieee802.org/16/meetings/mtg68/opening.html>).

Motion (13:35 h): "*To approve the agenda of Session #68.*"
Moved by Ronnie Murias, seconded by Jon Labs.
Motion approved by unanimous consent.

The Chair asked if there were any comments on the minutes of the previous session. None were received.

Motion (13:37 h): *"To approve the Minutes of Session #67 (IEEE 802.16-10/0038)."*
Moved by Ronnie Murias, seconded by Jon Labs.
Motion approved by unanimous consent.

Working Group Reports and Issues

The Chair displayed the Chair's Opening Plenary Presentation Slides, *IEEE 802.16-10/0042r1*. He reviewed the IEEE-SA affiliation disclosure requirements (reference <http://standards.ieee.org/faqs/affiliationFAQ.html>) and again reminded the WG attendees to accurately complete the affiliation field. The Chair reviewed the "Ethics policy" (reference <http://www.ieee.org/about/whatis/code.html>).

The Chair displayed the patent policy materials (reference <http://standards.ieee.org/board/pat/pat-material.html>) and presented Slides 1-3 from <http://standards.ieee.org/board/pat/pat-slideset.pdf>. The Chair asked if there were any questions, if anyone wanted to speak, and provided an opportunity for responses. No questions or responses were received. He then presented Slide 4 followed by Slide 0. The Chair asked if there were any questions, if anyone wanted to speak, and provided an opportunity for responses. No questions or responses were received. The Chair reminded the group that Letters of Assurance are available at the IEEE-SA web site. A database of LoAs (Letters of Assurances) related to IEEE 802.16 is available at <http://standards.ieee.org/db/patents/pat802_16.html>. The Chair instructed the Task Group chairs to repeat the patent policy rules in their groups per the details provided.

Copyright information is available at <http://ieee802.org/16/ipr/copyrights>. The Chair reminded the group that submissions which violate procedures will not be accepted <reference http://WirelessMAN.org/submit.html>.

The Chair discussed the IEEE 802 Rules documents, including Policies and Procedures, the Operations Manual and also the Working Group P&P <reference http://ieee802.org/devdocs.shtml>. He explained the role and responsibilities of the Chair and explained the issue of WG Domination

IEEE 802 Project Progression was presented as well as IEEE 802 Executive Committee (EC) Issues including Tutorials, other Working Group & Committee issues, possible rules changes and the possibility of 802 EC teleconferences.

There are three PARs under review and eligible for consideration at Fridays 802 EC meeting: 802.11 amendment for sub 1 GHz license-exempt operation PAR and 5C, 802.15.4 revision for low rate wireless PAN (LR-WPAN) PAR (no 5C as the scope adds no new features), 802.16 amendment for enhancements to provide functionalities specific to machine to machine communication PAR and 5 C. Persons with input on the 802.16 PAR were directed to discuss these in the Project Planning Committee. There were no comments raised regarding the other PARs.

The Chair provided a Working Group status update in *IEEE 802.16-10/0041r1.* IEEE Std 802.16h-2010 was approved June 17, 2010 and publication editing is now in process. During this meeting Harry Bims, LE TG Vice Chair, will be leading an effort to answer questions from the IEEE publication staff. Active projects are P802.16m (Advanced Air Interface) and P802.16n (Higher Reliability Networks). There also are activities in the Maintenance Task Group, the ITU-R Liaison Group, and the Project Planning Committee.

The Chair noted the summary report <http://wirelessman.org/meetings/mtg67/report.html> of Session #67, the Session #68 Document Guide and the Session #68 Schedule for the week, each of which were accessible from the local server at the meeting.

A WG Chair's "Open Office" is canceled due to overlapping meetings requiring the Chairs participation. Attendees were encouraged to meet and talk with the Chair after this opening plenary session, from 4:00 to 6:00 PM.

The schedule for the week was reviewed, noting that the calendar is available from the local web server.

Maintenance Task Group Report

Jon Labs presented the report *IEEE 802.16maint-10/0013*. Jon noted that any maintenance comments in the TGm Sponsor Ballot will be addressed in the Maintenance Task Group for resolution. The database containing the accepted maintenance change request comments is in IEEE 802.16maint-09/0007r8. A liaison statement *IEEE L802.16-10-/0070r1* was received from the WiMAX Forum TWG and will be addressed during this session.

TGm Report

Phil Barber, serving as Acting Chair of TGm for Session #67, presented the report *IEEE 802.16m-10/0020.* Phil discussed the results of the initial Sponsor Ballot which closed on July 9. The approval rate from this ballot is 58% which means that the scope of the subsequent recirculation ballot will include the entire document as open for comment. The plan for the week was discussed. The calendar for breakout sessions, the agenda and room allocations were reviewed.

Project Planning Ad Hoc Committee

Jose Puthenkulam presented the report *IEEE 802.16ppc-10/0006r2*. Jose reviewed the current status of the machine-to-machine (M2M) PAR & 5C development, *IEEE 802.16ppc-10/0003r6*. The group will address any comments received from the 802 community on the PAR and 5C, deadline is Wednesday 5:00 PM. A joint session with the GRIDMAN SG is scheduled, the goal is to make sure there is no overlap in Requirements developed in the two activities. A Project Planning Map was presented, listing topics which have previously been identified as potential areas for future work.

GRIDMAN Study Group

Tim Godfrey presented the report *IEEE 802.16gman-10/0023r1.* NESCOM approved the P802.16n PAR on June 18. A Call for Contributions on 802.16n System Requirements was issued on April 15 and remains open. In this session, the SG will focus on developing an outline of the 802.16n System Requirements Document. The draft agenda for the study group was reviewed. It was discussed that the future task group structure, following termination of the Study Group at the end of the week, will be discussed this week.

Liaison

ITU-R Liaison Group

The WG Chair presented the report *IEEE L802.16-10/0072* on behalf of Reza Arefi. The Chair reviewed relevant documents for the session, input documents, proposed objectives, the agenda for the week and the meeting schedule including room assignment.

Motion (15:02h): *"To authorize the ITU-R Liaison Group to draft documents regarding contributions as needed, tentatively approve them on behalf of the WG (subject to confirmation at the 802.16 Closing Plenary), submit them for 802.18 TAG review, and represent the WG with the 802.18 TAG."*
Moved by Lei Wang, second by Ronnie Murias. Motion is approved by unanimous consent.

Charge to Task Groups, Schedule for the week

The Chair reaffirmed that there were no changes to the room assignments.

Future Sessions

Session #68.5 (Special Interim):
16-19 August 2010 in Calgary, Canada
TGm only
Counts as an Interim Session towards membership
Quorum is not required per 802 WG Policies and Procedures
Session #69: (Interim): 13-16 September 2010 in St. Petersburg, Russia, hosted by Yota and by Intel Russia. Member Host: Alexander Maltsev.
Session #70 (Plenary): 8-11 November 2010 in Dallas, Texas, USA with IEEE 802 Plenary Session.
Session #71 (Interim): 10-13 January 2011 in Taipei.
Session #72 (Plenary): 14-17 March 2011 in Singapore with IEEE 802 Plenary Session.
Session #73 (Interim): 16-19 May 2011 in Banff, Alberta, Canada.
Session #74 (Plenary): 18-21 July 2011 in San Francisco, California, USA with IEEE 802 Plenary Session.
Session #75 (Interim): 19-22 September 2011: Interim Session; site to be determined by Session #70. Proposals solicited; please see IEEE 802.16 Interim Session Guidelines <reference http://ieee802.org/16/docs/04/80216-04_67.pdf>
Session #76 (Plenary): 7-10 Nov 2011 in Atlanta, Georgia, USA with IEEE 802 Plenary Session

New Business

Motion (15:20h): *"To authorize the Project Planning Committee to respond to the comments on M2M Par & 5C and submit the PAR & 5C to the 802 EC by the Wednesday 5 PM Deadline."*
Moved by Jose Puthenkulam, second by Tim Godfrey. Motion is approved by unanimous consent.

Closing

Motion (15.22h): *"To adjourn the Opening Plenary"*

Moved by Ronnie Murias, seconded by Phil Barber
Motion approved by unanimous consent.

IEEE 802.16 Session #68 Closing Plenary Meeting

Thursday, July 15, 2010, 17:17 – 21:58

Opening

The Chair of the 802.16 WG called the meeting to order at 17:17 hours local time. He welcomed the attendees and reviewed the draft Closing Plenary agenda (reference <http://ieee802.org/16/meetings/mtg68/closing.html>).

The Chair reminded the attendees of the patent policy and asked if anyone needed to have a review of the details. No request was made, and the meeting proceeded.

Approvals

Changes were made to the agenda and it was approved without objection.

Workgroup Issues

The Chair commented that attendance is recorded both by session registration and by the IMAT system. This meeting had approximately 165 persons attending the 802.16 session.

Maintenance Task Group

Jon Labs presented the report *IEEE 802.16maint-10/0016r1*. The task group processed a liaison letter from the WiMAX Forum, and drafted a reply in *IEEE L802.16-10/0077*. This reply was reviewed and updated in the closing plenary to revision 1.

Motion (17:38h): "*To forward L802.16-10/0077r1 as the proposed Liaison statement to the WiMAX TWG in response to L802.16-10/0070r1 and authorize the WG Chair to make any necessary editorial modifications.*"
Moved by Jon Labs, seconded by Phil Barber.
Approve: 29 Disapprove: 0 Abstain: 0
The motion passes

The current Maintenance database is IEEE 802.16maint-09/0007r9.

TGm

Phil Barber presented the report *IEEE 802.16m-10/0021r1*. All comments from the Sponsor Ballot were addressed. The resolutions were recorded in *IEEE 802.16-10/0040r2*. The current ballot status was reviewed.

Motion (17:46h): *"To approve the Session #68 resolutions to comments contained in 802.16-10/0040r2 and to authorize the editor to create the new draft P802.16m/D7"*
Moved by Rakesh Taori, seconded by Ronnie Murias
The motion is approved by unanimous consent.

Motion (17:48h): *"Request the WG Chair initiate a recirculation Sponsor Ballot on P802.16m/D7 in which the entire document is open for comment."*

There was discussion how to proceed when comments identify incomplete sections in the draft yet no text is available to complete the sections. The Chair commented that members are encouraged to review these comments and provide proposed remedies. Additionally members are invited to create lists of comments already received which identify areas lacking text, and submit this information into the next meeting.

The motion recorded above was moved by Lei Wang, seconded by Ronnie Murias.
The motion is approved by unanimous consent.

The project timeline from *IEEE 802.16m-10/0023* was presented. It was noted that the workplan is contained in *IEEE 802.16m-10/0010*.

GRIDMAN Study Group

Tim Godfrey presented the report *IEEE 802.16gman-10/0025*. A work plan was established and agreed. *IEEE 802.16gman-10/0024* was approved as "Working Draft for 802.16m system requirements Document."

It was noted that authorization for the Study Group expires after this meeting. The Chair announced that *GRIDMAN Task Group* will be formed to continue the work on this project. Tim Godfrey will be the Chair of the Task Group.

WG Project Planning Ad Hoc

Jose Puthenkulam presented the report *IEEE 802.16pcc-10/0010r2*. New areas for evolution of 802.16 were discussed. Comments on the M2M PAR & 5C were received from 802.11, 802.19 and Pat Thaler. A reply to each was generated.

The PAR & 5C were reviewed and changes agreed in *IEEE 802.16ppc-10/0003r9*.

Motion (20:50): *"To submit 802.16ppc-10/0003r9 as the draft 802.16p PAR & 5C for 802 EC approval. Also to authorize the Chair to make any editorial changes as necessary."*
Moved by Jose Puthenkulam, seconded by Eldad Zeira.
Approve: 36. Disapprove: 0. Abstain 0.
The motion carries.

An initial working draft of 802.16p Machine to Machine System Requirements Document was created in *IEEE 802.16ppc-10/0011*.

The 802.16 Project Planning Map was reviewed.

Liaison

ITU-R Liaison Group

Reza Arefi presented the report *IEEE L802.16-10/0079*.

Incoming liaison statements were reviewed. Outgoing liaisons were prepared for WiMAX Forum, Japan and TTA.

Motion (21:10h): "*To approve the following documents and authorize the WG Chair to forward them to their respective recipients subject to any editorial corrections including additions to the cc list.*"

IEEE L802.16-10/0075 – Liaison statement to Japan concerning the IMT-Advanced development process
IEEE L802.16-10/0076 – Liaison statement to ARIB concerning the IMT-Advanced development process
IEEE L802.16-10/0078 – Liaison statement to WiMAX Forum concerning Inclusion of information on supported frequency bands and unwanted emissions in IEEE P802.16m draft standard

Motion moved by Reza Arefi, seconded by Matt Sherman
Approve: 40. Disapprove: 0. Abstain: 0.
The motion carries.

802.21 Report

Anthony Chan presented the report *IEEE L802.16-10/0080r1*.

802.21a Security Extension is expected to begin Working Group Letter Ballot after the September session.
802.21b Handovers with Downlink Only Technologies is approved to begin Working Group Letter Ballot.
802.21c Optimized Single Radio Handover is under discussion.
Study Group for Wireless Network Management is identifying use cases and discussing if there is overlap of the SG with 802.19.1.

802.19 Report

Mat Sherman provided a verbal report.

The 802.19 WG reviewed and discussed the 802 Architecture work. A call for proposals of White Space Coexistence is expected in September. 802.19 is hosting a White Space Coexistence workshop on July 16.

Future Sessions

<reference http://ieee802.org/16/calendar.html>

Session #68.5 (Special Interim):	
	See <http://wirelessman.org/meetings/mtg685/index.html> 16-19 August 2010 in Calgary, Canada TGm only Counts as an Interim Session towards membership This meeting will close by 5:00 PM on Thursday. Quorum is not required per 802 WG Policies and Procedures
Session #69 (Interim):	13-16 September 2010 in St. Petersburg, Russia, hosted by Yota and by Intel Russia. Member Host: Alexander Maltsev. See <http://wirelessman.org/meetings/mtg69/index.html> Note the section "Visa Information"
Session #70 (Plenary):	8-11 November 2010 in Dallas, Texas, USA with IEEE 802 Plenary Session.
Session #71 (Interim):	10-13 January 2011 in Taipei.
Session #72 (Plenary):	14-17 March 2011 in Singapore with IEEE 802 Plenary Session.
Session #73 (Interim):	16-19 May 2011 in Banff, Canada.
Session #74 (Plenary):	18-21 July 2011 in San Francisco, California, USA with IEEE 802 Plenary Session.
Session #75 (Interim):	19-22 September 2011 site to be determined no later than Session #70. Proposals solicited; please see IEEE 802.16 Interim Session Guidelines. <reference http://ieee802.org/16/docs/04/80216-04_67.pdf>
Session #76 (Plenary):	7-10 Nov 2011 in Atlanta, Georgia, USA with IEEE 802 Plenary Session.

Publicity

The Chair will prepare the Session #68 Report.

WG Issues

Motion (21:27h): "*To authorize to TGm to resolve comments received in sponsor ballot recirculation number 1 of P802.16m/D7 and prepare P802.16m/D8*"
Moved by Phil Barber, second by Ronnie Murias
The motion carries by unanimous consent.

802 Executive Committee Meeting:
The Chair will submit the updated version of the M2M PAR & 5C to the 802 EC for their Friday meeting.

Editor's Meeting:
Will be held 9:00 – 12:00 on Friday in the Bush room.

New Business

Phil Barber provided an update on the 802 ARCH Committee
The Arch committee is working on a revision of the 802 Architecture document. Phil has created and submitted *IEEE C802.16-10/0030r1* containing the 802.16 reference architecture from 802.16-2009.

802.18 contributions for the 802 EC meeting
Document 18-10-0046-03-0000-cmts-innocation-noi-09-157-doc is a statement to the US FCC. In this contribution 802 recommends against establishing receiver standards.

Document 18-10-0043-03-0000-update-itu-r-wp5a-report-ims-crs.doc is a contribution to WP 5A on Cognitive Radio. The current WP 5A report references 802.22. This contribution updates WP 5A on updates to the 802.22 PAR.

Closing

Motion (21:58 h): *"To adjourn."*

Moved by Jon Labs, seconded by Ronnie Murias.
Motion carries by unanimous consent.

Registration List: IEEE 802.16 Session #68

Updated 2010-08-02 (MT)

164 attendees registered and/or in the attendance logs, including at least 150 with "participation" credit

Participation Credit	**Name\Family**	**Name \Given**	**Affiliation***	**City**	**State\Province**	**Country/ Admin**
Yes	Agiwal	Anil	Samsung Electronics	Bangalore		India
Yes	Ahmadi	Sassan	Intel Corporation	Hillsboro	OR	USA
Yes	Ahmed	Hanan	Huawei Technologies Co., Ltd.			
Yes	Arefi	Reza	Intel Corporation	Hillsboro	OR	USA
Yes	Arrington	Arthur	Air Network Solutions			USA
Yes	Baek	Youngkyo	Samsung Electronics	Suwon	Gyeonggi-do	Korea
No++	Bahng	Seungjae	ETRI	Daejeon	Chungcheongnam-do	Korea
Yes	Barber	Phillip	Huawei Technologies Co., Ltd.	Plano	TX	USA
Yes	Bims	Harry	Bims Laboratories, Inc.	Cupertino	CA	USA
Yes	Bohyun	Kang	Samsung Electronics	Suwon	Gyeinggi-do	Korea
Yes	Cha	Jaesun	Electronics and Telecommunications Research Instititute (ETRI)	Daejeon		Korea
Yes	Chang	Kim	Huawei Technologies Co., Ltd.			
Yes	Chang	Sung-Cheol	Electronics and Telecommunications Research Instititute (ETRI)	Daejeon		Korea
Yes	Chang	YoungBin	Samsung Electronics	Suwon	Gyeonggi-do	Korea
Yes	Chen	Bin	Huawei Technologies Co., Ltd.			

Yes	Chen	Chiu-Wen	Institute for Information Industry	Taipei		Taiwan
Yes	Chen	Chungpao	ITRI			
Yes	Chen	Whai-En	National Ilan University	I-Lan	Taiwan	Taiwan
Yes	Chen	Yung-Han	ITRI	Chutung, Hsinchu		Taiwan
Yes	Chen	Yuqin	ZTE Corporation	Shenzhen	Guangdong	China
Yes	Chien	Chun-Che	Institute for Information Industry	Taipei City		Taiwan
Yes	Chiu	Chun-Yuan	ITRI	Hsin-Chu	Taiwan	Taiwan
Yes	Cho	Jaeweon	Samsung Electronics	Suwon	Gyeonggi	Korea
Yes	Cho	Youngbo	Samsung Electronics	Suwon-si	Gyeonggi-do	Korea
Yes	Choi	Hyoung-Jin	TTA	Seongnam	Gyeonggi-do	Korea
Yes	Choi	Jinsoo	LG ELECTRONICS			Korea
Yes	Choi	Yang-Seok	Intel Corporation	Hillsboro	OR	USA
Yes	Chou	Chao-Chin	MediaTek Inc.	Hsinchu		Taiwan
Yes	Chou	Joey	Intel Corporation	Chandler	AZ	USA
Yes	Chun	Jin Young	LG ELECTRONICS	Anyang	Gyeonggi-do	Korea
Yes	Colban	Erik	NextWave Wireless Inc.	San Diego	CA	USA
Yes	Crowley	Steven	NTT DoCoMo, Inc.			USA
Yes	Cudak	Mark	Motorola, Inc.	Arlington Heights, IL 60004	IL	USA
Yes	Cummings	George	Motorola, Inc.			USA
Yes	Davydov	Alexey	Intel Corporation	Nizhny Novgorod		Russia
Yes	Dhaliwal	Upkar	Future Wireless Technologies	San Diego	CA	USA
Yes	Fan	Linghang	NEC	London		UK
Yes	Fang	Huiying	ZTE Corporation	Shenzhen	Guangdong	China
Yes	Fang	Yu-Chuan	Industrial Technology Research Institute	Chutung Hsinchu	Taiwan	Taiwan
Yes	Fu	I-Kang	MediaTek Inc.	Hsinchu		Taiwan
Yes	Gal	Dan	ALCATEL-LUCENT	Morris Plains	NJ	USA

Yes	Gilin	Michael	RuggedCom, Inc.			
Yes	Godfrey	Tim	Electric Power Research Institute, Inc. (EPRI)			
Yes	Gundlach	Michael	Nokia Siemens Networks	Munich		Germany
Yes	Hillery	William	Motorola, Inc.	Arlington Heights	IL	USA
Yes	Himayat	Nageen	Intel Corporation	Santa Clara	CA	USA
Yes	Hsiao	Ying-Chuan	Industrial Technology Research Institute	Chutung, Hsinchu	Taiwan	Taiwan
Yes	Hsieh	Ching-Tarng	Industrial Technology Research Institute	Hsinchu		Taiwan
Yes	Hsieh	Yu-Tao	ITRI	Hsinchu		Taiwan
Yes	Hsu	Chun-Yen	Institute for Information Industry	Taipei	NIL	Taiwan
Yes	Hsuan	Yi	Intel Corporation	Santa Clara	CA	USA
Yes	Ikeda	Tetsu	NEC Corporation	Kawasaki		Japan
Yes	Imata	Satoshi	KDDI R and D Laboratories Inc.			Japan
Yes	Jan	Yih Guang	TKU	Taipei		Taiwan
Yes	Jang	Jaehyuk	Samsung Electronics	Suwon-si	Gyeonggi-do	Korea
Yes	Jeon	Hongseok	Electronics and Telecommunications Research Instititute (ETRI)	Daejeon	Chung-Nam	Korea
Yes	Johnson	Brian	Texas Instruments	Germantown	MD	USA
Yes	Johnsson	Kerstin	Intel Corporation	Santa Clara	CA	USA
Yes	Josiam	Kaushik	Samsung Electronics	Richardson	Texas	USA
Yes	Julka	Vibhor	Huawei Technologies Co., Ltd.			
Yes	Jung	Inuk	LG ELECTRONICS	Anyang	Gyongkido	Korea
Yes	Jung	Soojung	Electronics and Telecommunications Research Instititute (ETRI)			Korea
Yes	Kang	Heewon	Samsung Electronics			Korea

Yes	Kang	Hyunjeong	Samsung Electronics	Suwon	Gyeonggi-do	Korea
Yes	Kanzaki	Hajime	Hitachi Ltd.	Kokubunji-shi	Tokyo	Japan
Yes	Kapadia	Prateek	TICET			India
Yes	Karandikar	Abhay	IIT Bombay			
Yes	Khojastepour	Mohammad	NEC Laboratories America, Inc.	Princeton	NJ	USA
Yes	Khoryaev	Alexey	Intel Corporation	Nizhny Novgorod		Russia
Yes	Kim	Eunkyung	Electronics and Telecommunications Research Instititute (ETRI)	Daejeon	Daejeon	Korea
Yes	Kim	Jeongki	LG ELECTRONICS	Anyang-Shi	Gyeonggi-do	Korea
No	Kim	Kanghee	Electronics and Telecommunications Research Institute (ETRI)	Daejeon	Chungcheongnam-do	Korea
Yes	Kim	Namgi	Kyonggi University	suwon	Kyounggi	Korea
Yes	Kim	Ronny (Yong-Ho)	LG ELECTRONICS	Anyang-shi	Gyeonggi-do	Korea
Yes	Kim	Sangheon	Samsung Electronics	Suwon	Gyeonggi-do	Korea
No	Kim	Seokki	Electronics and Telecommunications Research Instititute (ETRI)	Daejeon	Daejeon	Korea
Yes	Kim	Taeyoung	Samsung Electronics	Suwon	Gyeonggi-do	Korea
Yes	Kim	Young Kyun	ETRI - Electronics and Telecommunications Research Institute	suwon	Gyeonggi-do	Korea
Yes	Klutto Milleth	J.	CEWiT	Chennai	Tamilnadu	India
No	Kuchi	Kiran Kumar	CEWiT	Chennai	Jeollanam-do	India
Yes	Kwak	Jin-Sam	LG ELECTRONICS	Anyang	Gyeonggi-do	Korea
Yes	Kwon	Dong Seung	Electronics and Telecommunications Research Institute (ETRI)	Daejeon	Chungcheongnam-do	Korea
Yes	Labs	Jonathan	Wavesat, Inc.	Dorval	PQ	Canada

Yes	Lee	Anseok	Electronics and Telecommunications Research Instititute (ETRI)	Daejeon	Daejeon	Korea
Yes	Lee	Hyun	ETRI - Electronics and Telecommunications Research Institute	Daejeon		Korea
No	Lee	Seung-Jae	LG ELECTRONICS	Seoul	Seoul	Korea
Yes	Lee	Youn-Tai	Institute for Information Industry	Taipei	Taiwan	Taiwan
Yes	Li	Ying	Samsung Electronics	Richardson	TX	USA
Yes	Liao	Pei-Kai	MediaTek Inc.			Taiwan
Yes	Lim	Chiwoo	Samsung Electronics	SUWON	Gyeonggi-do	KOREA
Yes	Lin	Jia	Huawei Technologies Co., Ltd.	Shenzhen	GuangDong	China
Yes	Lin	Kun-Yi	National Taipei University of Technology	Taipei	Taiwan	Taiwan
Yes	Lin	Ping-Chen	National Taiwan University of Science and Technology			
Yes	Lin	Yi-Ting	Institute for Information Industry	Taipei		Taiwan
Yes	Lin	Yu-Chan	National Ilan University	ILAN		Taiwan
Yes	Liu	Yang	ZTE Corporation	Shenzhen	Guangdong	China
Yes	Madihian	Mohammad	MEDIWAVE LLC		NJ	USA
Yes	Maeder	Andreas	NEC Corporation	Heidelberg	DE	Germany
Yes	Mao	Ronald	Huawei Technologies Co., Ltd.	San Diego	CA	USA
Yes	Marks	Roger	WiMAX Forum	Denver	CO	USA
Yes	Masters	Jeffery	Axxcelera Broadband Wireless	Richmond	VA	USA
Yes	Meddour	Djamal-Eddine	France Telecom	Lannion		France
Yes	Mohanty	Shantidev	Intel corporation			USA

No++	Molisch	Andreas	Mitsubishi Electric	Cambridge	MA	USA
Yes	Murias	Ronald	InterDigital Communications, LLC	Calgary	AB	Canada
No	Ng	Put Fan	Rogers Communications Inc.	Brampton	ON	Canada
Yes	Nguyen	An	National Communications System	Falls Church	VA	USA
Yes	Nigam	Anshuman	Samsung Electronics	Bangalore		India
Yes	Niu	Huaning	Intel Corporation	Santa clara	CA	USA
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Yes	Okuda	Masato	FUJITSU	Kawasaki	Kanagawa	Japan
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No	Park	Youn Ok	wg802.16	Daejeon	Chungcheongnam-do	Korea
Yes	Pathmasuntharam	Jaya Shankar	Institute for Infocomm Research	Singapore		Singapore
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Yes	Probasco	Scott	Nokia	Irving	TX	USA
Yes	Puthenkulam	Jose	Intel Corporation	Hillsboro	OR	USA
Yes	Qin	Fei	Datang Mobile Communication	Beijing		China
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Yes	Schumacher	Joseph	Motorola, Inc.	Arlington Heights	IL	USA
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Yes	Son	Jung Je	Samsung Electronics	Seoul	Gyeonggi-do	Korea
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Yes	Wang	Haiguang	Institute for Infocomm Research			Singapore
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Yes	Wang	Lei	InterDigital Communications, LLC	San Diego	CA	USA
Yes	Wang	Limei	Huawei Technologies Co., Ltd.			China
Yes	Wang	Ping	Intel Corporation	Beijing	Beijing	China
Yes	Wang	Shao-Cheng	Intel Corporation	hillsboro	or	US
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The IEEE 802.16 Working Group on Broadband Wireless Access Standards

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Updated: 2010-08-02 to account for Session #68.

Number of members: 264
Next scheduled update: following Session #70

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